



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Young Chul LEE et al. Confirmation No: 9936  
Appl. No. : 10/630,746  
Filed : July 31, 2003  
Title : THREE DIMENSIONAL MULTILAYER RF MODULE HAVING  
AIR CAVITIES AND METHOD FABRICATING SAME  
  
TC/A.U. : 1772  
Examiner : W. P. Watkins III  
  
Docket No.: : LEEY3017/REF  
Customer No: : 23364

**REQUEST FOR RECONSIDERATION**

**MS AF**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of July 26, 2005 which is a Final Rejection, in connection with the above-identified application. The period for response to this Official Action has been extended to expire on December 26, 2005 by the filing herewith of a Petition for a Two Month Extension of Time and payment of the required fee.

The rejection of claims 1, 2 and 4 under 35 U.S.C. 102(b) as being anticipated by Johnson et al and the rejection of claim 3 under 35 U.S.C. 103(a) as being obvious over Johnson et al. (U.S. 6,278,049) have been carefully considered but are most respectfully traversed.

By way of review, the presently claimed invention is directed to a multilayer RF module. In a RF module, there occurs a significant increase in the capacitive loading of the interconnect nodes between chips because of the high dielectric constant of the ceramic layers. Additionally, a higher dielectric constant lowers the attainable characteristic impedance for many applications. Accordingly, the air cavities of the present invention serve to reduce the dielectric constant of the ceramic layers.